

WHAT IS CLAIMED IS:**1. A image sensor module, comprising:**

a substrate having a upper surface and a lower surface, the upper surface formed with a plurality of first connected ends, the lower surface formed with a 5 plurality of second connected ends :

a photosensitive chip arranged at the upper surface of the substrate, and electrically connected the first connected ends by a plurality of wires ;

a lens holder formed with a penetrated hole at a central thereof, an internal thread being formed on the inner wall of the penetrated hole, the lens holder being 10 mounted on the upper surface of the first substrate to encapsulate the photosensitive chip ; and

a lens barrel arranged within the penetrate hole of the lens holder and is formed with an external thread, which is screwed to the internal thread of the lens holder, the lens barrel being formed with a chamber and an opening 15 communicating the chamber, a aspheric and a transparent layer are arranged within the chamber.

2. The image sensor module according to claim 1, wherein the transparent layer is an infrared filter.

3. a method for manufacturing an image sensor module, comprising the 20 steps :

providing a substrate having a upper surface and a lower surface, the upper surface formed with a plurality of first connected ends, the lower surface formed with a plurality of second connected ends ;

5. providing a photosensitive chip arranged at the upper surface of the substrate, and electrically connected the first connected ends by a plurality of wires ;

10 providing a lens holder formed with a penetrate hole at a central thereof, an internal thread being formed on the inner wall of the penetrate hole, the lens holder being mounted on the upper surface of the first substrate to encapsulate the photosensitive chip ; and

15 providing a lens barrel arranged within the penetrate hole of the lens holder and is formed with an external thread, which is screwed to the internal thread of the lens holder, the lens barrel being formed with a chamber and an opening communicating the chamber, a aspheric and a transparent layer are arranged within the chamber.